2SK1566, 2SK1567

Silicon N-Channel MOS FET

HITACHI

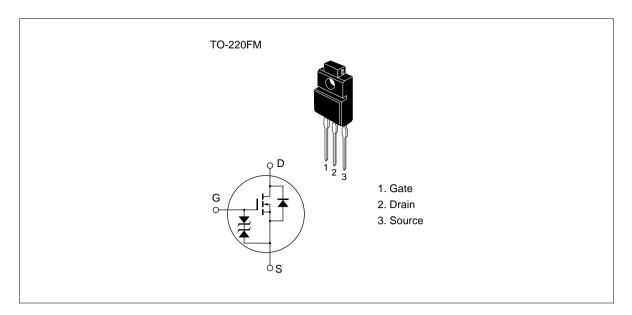
Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- Suitable for switching regulator and DC-DC converter

Outline





2SK1566, 2SK1567

Absolute Maximum Ratings (Ta = 25°C)

Item		Symbol	Ratings	Unit
Drain to source voltage	2SK1566	V _{DSS}	450	V
	2SK1567		500	
Gate to source voltage		V _{GSS}	±30	V
Drain current		I _D	7	А
Drain peak current		I _{D(pulse)} *1	28	А
Body to drain diode reverse	e drain current	I _{DR}	7	А
Channel dissipation		Pch*2	35	W
Channel temperature		Tch	150	°C
Storage temperature		Tstg	-55 to +150	°C

Note

- 1. PW \leq 10 μ s, duty cycle \leq 1%
- 2. Value at $T_c = 25^{\circ}C$

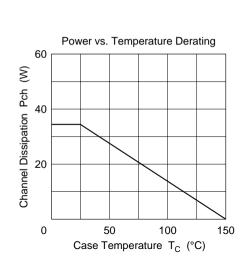
Electrical Characteristics ($Ta = 25^{\circ}C$)

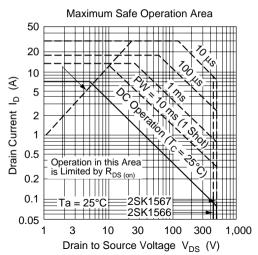
Item		Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source	2SK1566	$V_{(BR)DSS}$	450	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
breakdown voltage	2SK1567	-	500	_			
Gate to source breakdown voltage		$V_{(BR)GSS}$	±30	_	_	V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current		I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0$
Zero gate voltage	2SK1566	I _{DSS}	_	_	250	μΑ	$V_{DS} = 360 \text{ V}, V_{GS} = 0$
drain current	2SK1567	-					$V_{DS} = 400 \text{ V}, V_{GS} = 0$
Gate to source cutoff	voltage	$V_{GS(off)}$	2.0	_	3.0	V	$I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Static Drain to source	2SK1566	R _{DS(on)}	_	0.6	8.0	Ω	$I_D = 4 \text{ A}, V_{GS} = 10 \text{ V}^{*1}$
on state resistance	2SK1567	-	_	0.7	0.9	_	
Forward transfer admittance		yfs	4.0	6.5	_	S	$I_D = 4 \text{ A}, V_{DS} = 10 \text{ V}^{*1}$
Input capacitance		Ciss	_	1050	_	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$
Output capacitance		Coss	_	280	_	pF	f = 1 MHz
Reverse transfer capacitance		Crss	_	40	_	pF	_
Turn-on delay time		t _{d(on)}	_	15	_	ns	$I_D = 4 \text{ A}, V_{GS} = 10 \text{ V},$
Rise time		t _r	_	55	_	ns	$R_L = 7.5 \Omega$
Turn-off delay time		t _{d(off)}	_	95	_	ns	_
Fall time		t _f	_	40	_	ns	_
Body to drain diode forward voltage		V_{DF}		0.95		V	$I_F = 7 \text{ A}, V_{GS} = 0$
Body to drain diode reverse recovery time		t _{rr}		320		ns	$I_F = 7 \text{ A}, V_{GS} = 0,$ $di_F/dt = 100 \text{ A/}\mu\text{s}$

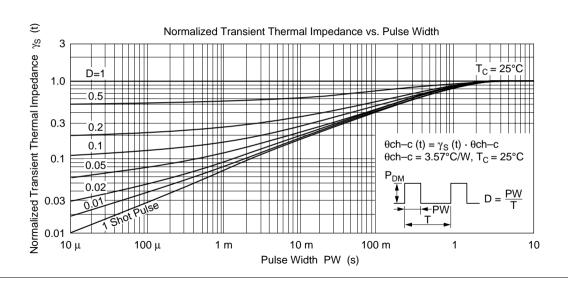
Note 1. Pulse test

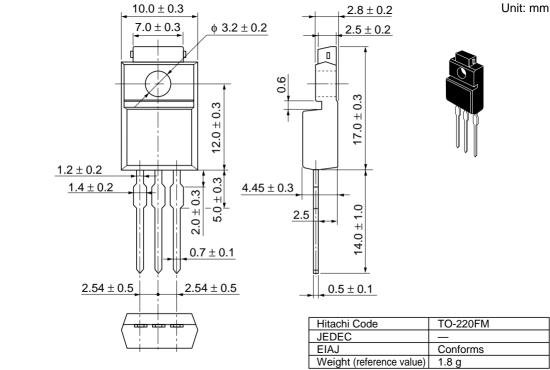
See characteristic curves of 2SK1157, 2SK1158.

2SK1566, 2SK1567









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